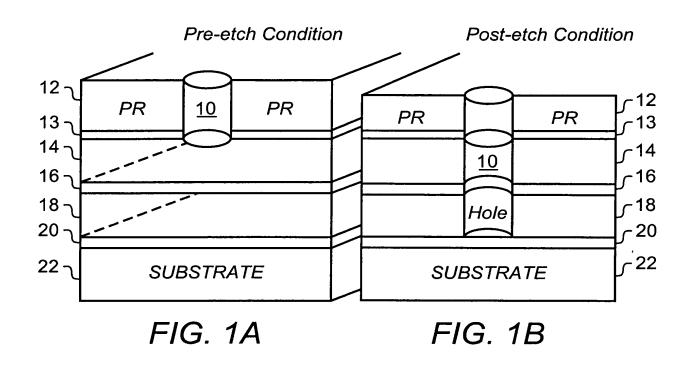
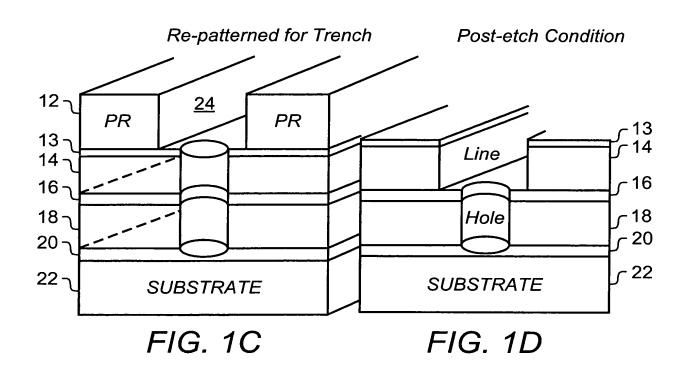
APPLN. FILING DATE: MARCH 30, 2001
TEE: METHOD OF PLASMA ETCHING.

IN LITOR(S): SI YI LI ET AL.

APPLICATION SERIAL NO: 09/820,695

SHEET 1 of 5

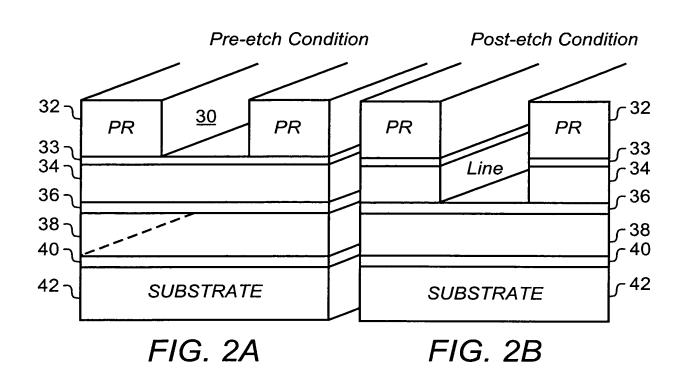


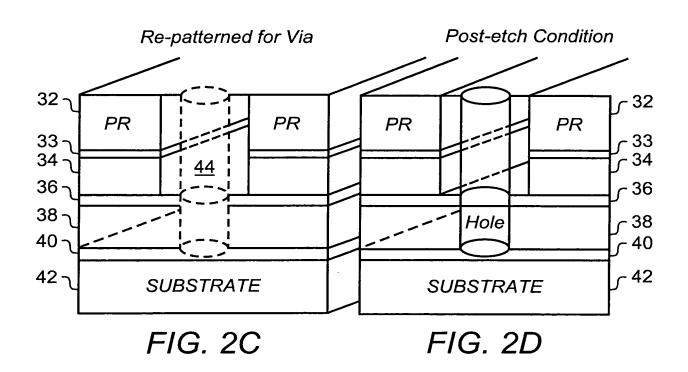


APPLN. FILING DATE: MARCH 30, 2001
TITLE METHOD OF PLASMA ETCHING...

INVER R(S): SI YI LI ET AL.

APPLICATION SERIAL NO: 09/820,695 SHEET 2 of 5



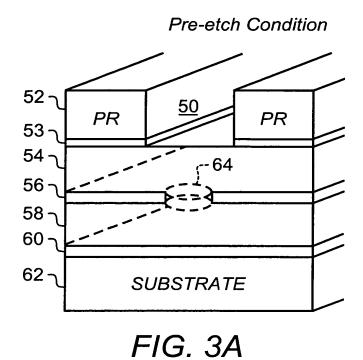


APPLN. FILING DATE: MARCH 30, 2001 TITLE METHOD OF PLASMA ETCHING...

INVENTOR(S): SI YI LI ET AL.

APPLICATION SERIAL NO: 09/820,695

SHEET 3 of 5



Post-etch Condition

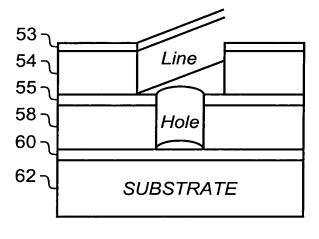
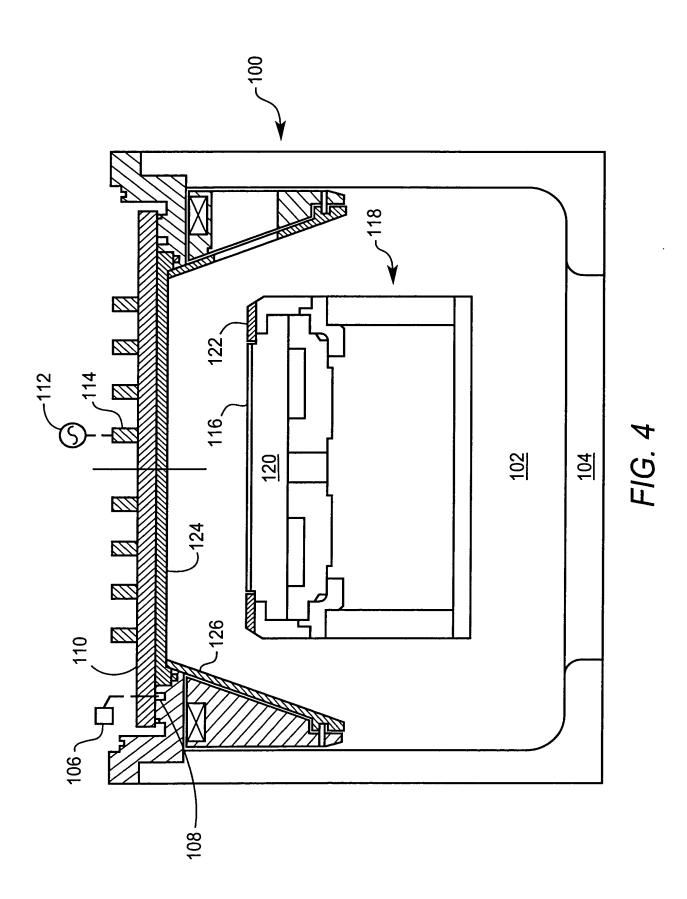


FIG. 3B

APPLN. FILING DATE: MARCH 30, 2001
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INVENT (S): SI YI LI ET AL.
APPLICATION SERIAL NO: 09/820,695

SHEET 4 of 5



APPLN. FILING DATE: MARCH 30, 2001
TO LE: METHOD OF PLASMA ETCHING
ENTOR(S): SI YI LI ET AL.
APPLICATION SERIAL NO: 09/820,695

SHEET 5 of 5

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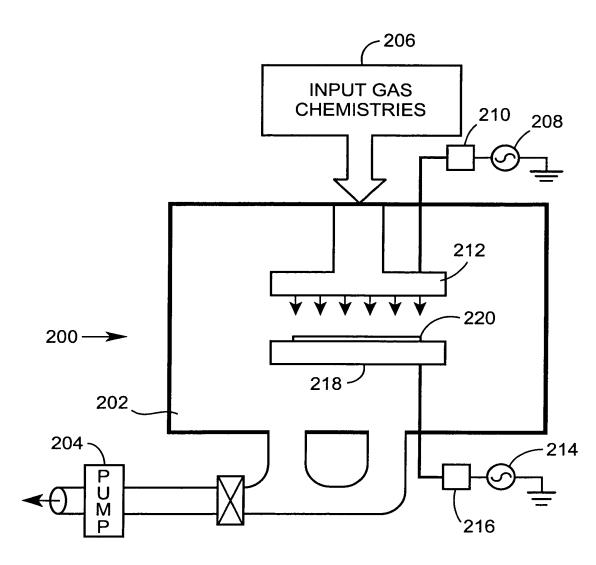


FIG. 5